

## NCE N-Channel Super Trench II Power MOSFET

### Description

The NCEP072N10A uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

### General Features

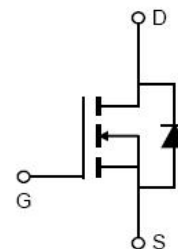
- $V_{DS} = 100V, I_D = 88A$   
 $R_{DS(ON)} = 6.2m\Omega$  (typical) @  $V_{GS} = 10V$   
 $R_{DS(ON)} = 8.4m\Omega$  (typical) @  $V_{GS} = 4.5V$
- Excellent gate charge x  $R_{DS(on)}$  product(FOM)
- Very low on-resistance  $R_{DS(on)}$
- 175°C operating temperature
- Pb-free lead plating

**100% UIS TESTED!**  
**100%  $\Delta V_{ds}$  TESTED!**

TO-220



Top View



Schematic Diagram

### Package Marking and Ordering Information

| Device Marking | Device      | Device Package | Reel Size | Tape width | Quantity |
|----------------|-------------|----------------|-----------|------------|----------|
| NCEP072N10A    | NCEP072N10A | TO-220-3L      | -         | -          | -        |

### Absolute Maximum Ratings ( $T_c = 25^\circ C$ unless otherwise noted)

| Parameter  | Symbol             | Limit      | Unit          |
|--|--------------------|------------|---------------|
| Drain-Source Voltage                             | $V_{DS}$           | 100        | V             |
| Gate-Source Voltage                              | $V_{GS}$           | $\pm 20$   | V             |
| Drain Current-Continuous                         | $I_D$              | 88         | A             |
| Drain Current-Continuous( $T_c = 100^\circ C$ )  | $I_D(100^\circ C)$ | 63         | A             |
| Pulsed Drain Current                             | $I_{DM}$           | 352        | A             |
| Maximum Power Dissipation                        | $P_D$              | 125        | W             |
| Derating factor                                  |                    | 0.83       | W/ $^\circ C$ |
| Single pulse avalanche energy (Note 5)           | $E_{AS}$           | 387        | mJ            |
| Operating Junction and Storage Temperature Range | $T_J, T_{STG}$     | -55 To 175 | $^\circ C$    |

### Thermal Characteristic

|   |                 |     |              |
|---|-----------------|-----|--------------|
| Thermal Resistance, Junction-to-Case (Note 2) | $R_{\theta JC}$ | 1.2 | $^\circ C/W$ |
|---|-----------------|-----|--------------|

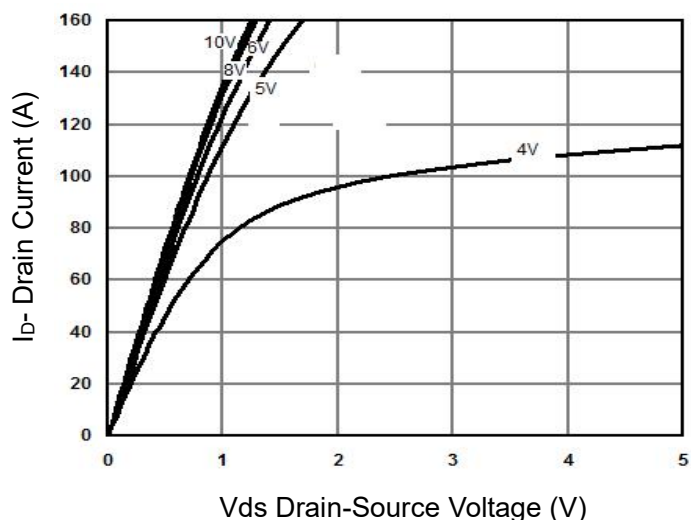
## Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

| Parameter                          | Symbol              | Condition  | Min | Typ  | Max  | Unit |
|------------------------------------|---------------------|--|-----|------|------|------|
| Off Characteristics                |                     |  |     |      |      |      |
| Drain-Source Breakdown Voltage     | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250μA  | 100 |      | -    | V    |
| Zero Gate Voltage Drain Current    | I <sub>DSS</sub>    | V <sub>DS</sub> =100V,V <sub>GS</sub> =0V  | -   | -    | 1    | μA   |
| Gate-Body Leakage Current          | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V  | -   | -    | ±100 | nA   |
| On Characteristics (Note 3)        |                     |  |     |      |      |      |
| Gate Threshold Voltage             | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA                              | 1.2 | 1.7  | 2.5  | V    |
| Drain-Source On-State Resistance   | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =44A  | -   | 6.2  | 7.2  | mΩ   |
|                                    |                     | V <sub>GS</sub> =4.5V, I <sub>D</sub> =44A   |     | 8.4  | 9.6  |      |
| Forward Transconductance           | g <sub>FS</sub>     | V <sub>DS</sub> =5V,I <sub>D</sub> =44A  |     | 60   | -    | S    |
| Dynamic Characteristics (Note4)    |                     |  |     |      |      |      |
| Input Capacitance                  | C <sub>iss</sub>    | V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,<br>F=1.0MHz                                | -   | 4120 | -    | PF   |
| Output Capacitance                 | C <sub>oss</sub>    |  | -   | 322  | -    | PF   |
| Reverse Transfer Capacitance       | C <sub>rss</sub>    |  | -   | 12.5 | -    | PF   |
| Switching Characteristics (Note 4) |                     |  |     |      |      |      |
| Turn-on Delay Time                 | t <sub>d(on)</sub>  | V <sub>DD</sub> =50V,I <sub>D</sub> =44A,<br>V <sub>GS</sub> =10V,R <sub>G</sub> =3Ω | -   | 17   | -    | nS   |
| Turn-on Rise Time                  | t <sub>r</sub>      |  | -   | 11   | -    | nS   |
| Turn-Off Delay Time                | t <sub>d(off)</sub> |  | -   | 36   | -    | nS   |
| Turn-Off Fall Time                 | t <sub>f</sub>      |  | -   | 9    | -    | nS   |
| Total Gate Charge                  | Q <sub>g</sub>      | V <sub>DS</sub> =50V,I <sub>D</sub> =44A,<br>V <sub>GS</sub> =10V                    | -   | 81   | -    | nC   |
| Gate-Source Charge                 | Q <sub>gs</sub>     |  | -   | 13.9 |      | nC   |
| Gate-Drain Charge                  | Q <sub>gd</sub>     |  | -   | 21.3 |      | nC   |
| Drain-Source Diode Characteristics |                     |  |     |      |      |      |
| Diode Forward Voltage (Note 3)     | V <sub>SD</sub>     | V <sub>GS</sub> =0V,I <sub>S</sub> =44A  | -   |      | 1.2  | V    |
| Diode Forward Current (Note 2)     | I <sub>S</sub>      |  | -   | -    | 88   | A    |
| Reverse Recovery Time              | t <sub>rr</sub>     | T <sub>J</sub> = 25°C, I <sub>F</sub> =44A   | -   | 62   | -    | nS   |
| Reverse Recovery Charge            | Q <sub>rr</sub>     | di/dt = 100A/μs(Note3)   | -   | 109  | -    | nC   |

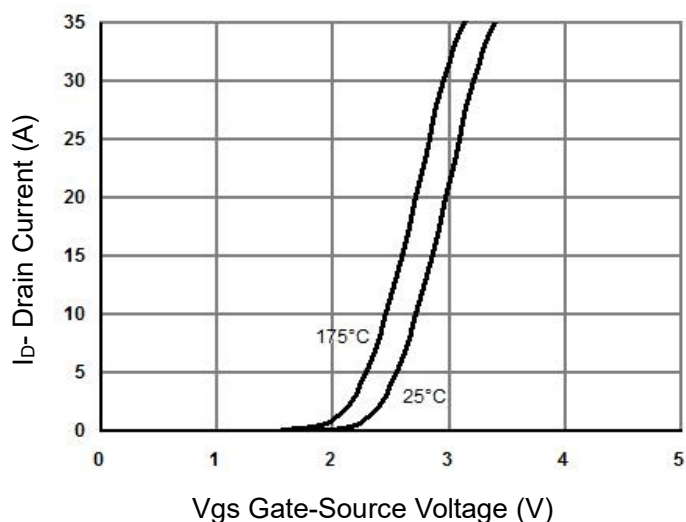
### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition : T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, L=0.5mH, R<sub>G</sub>=25Ω

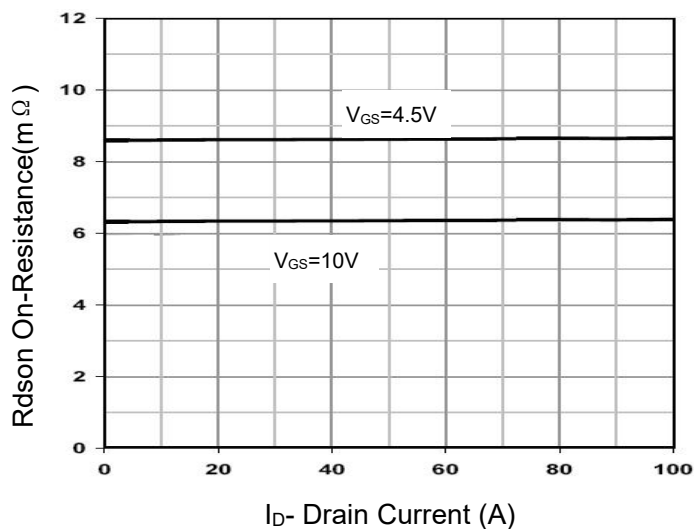
## Typical Electrical and Thermal Characteristics



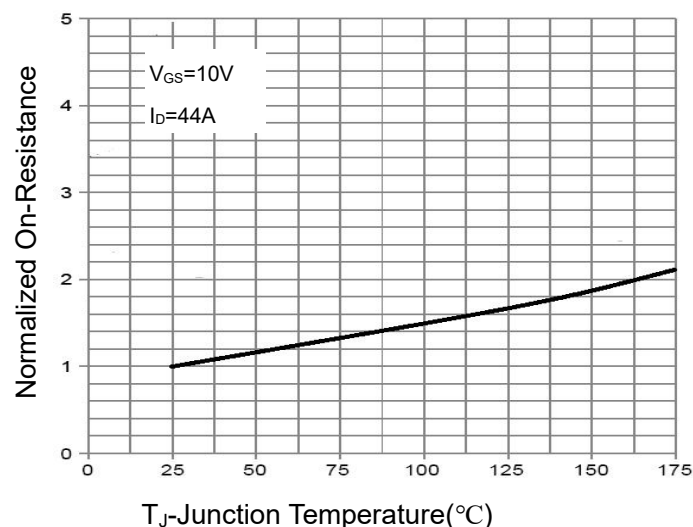
**Figure 1 Output Characteristics**



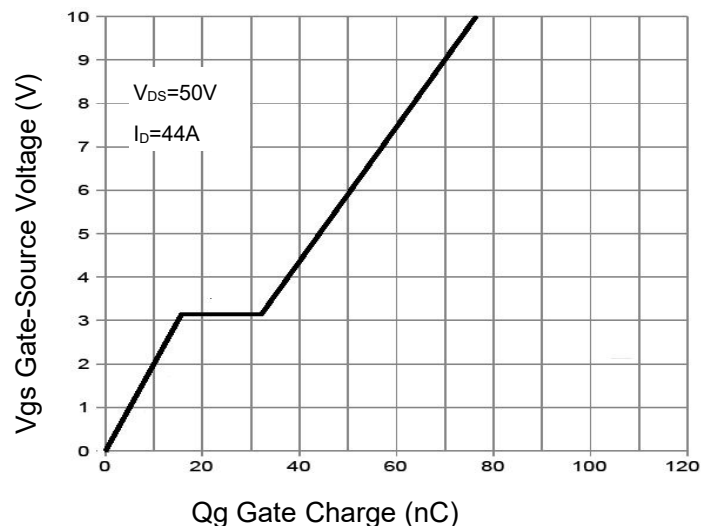
**Figure 2 Transfer Characteristics**



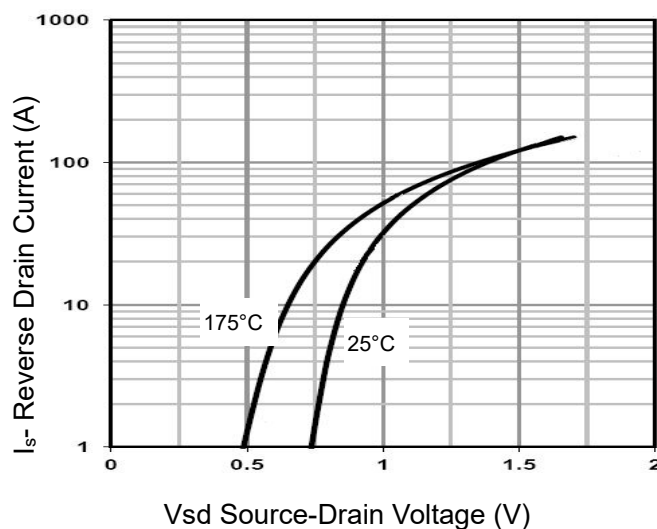
**Figure 3 Rdson- Drain Current**



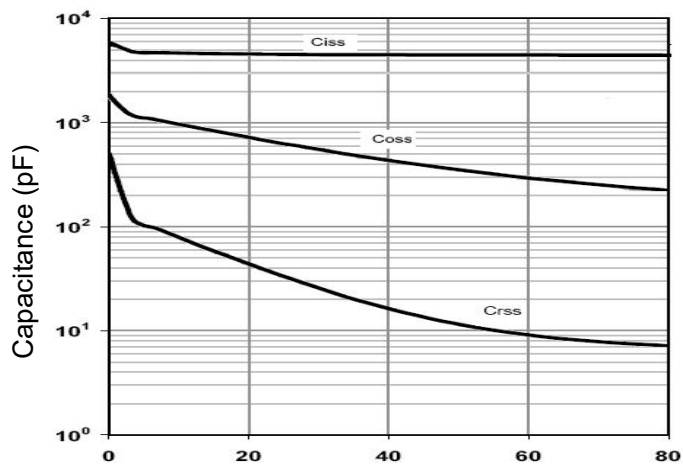
**Figure 4 Rdson-Junction Temperature**



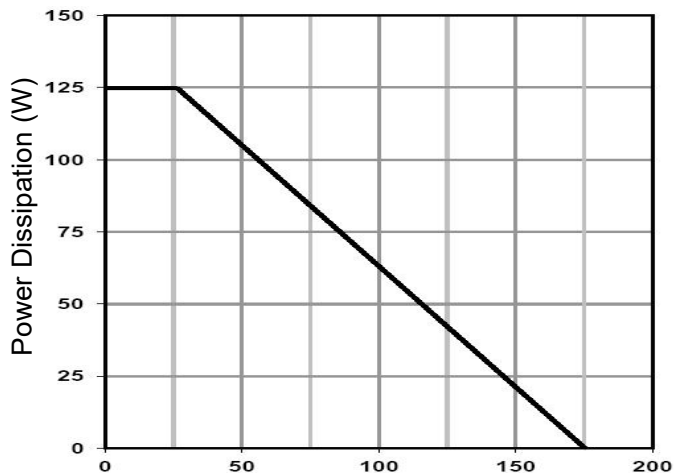
**Figure 5 Gate Charge**



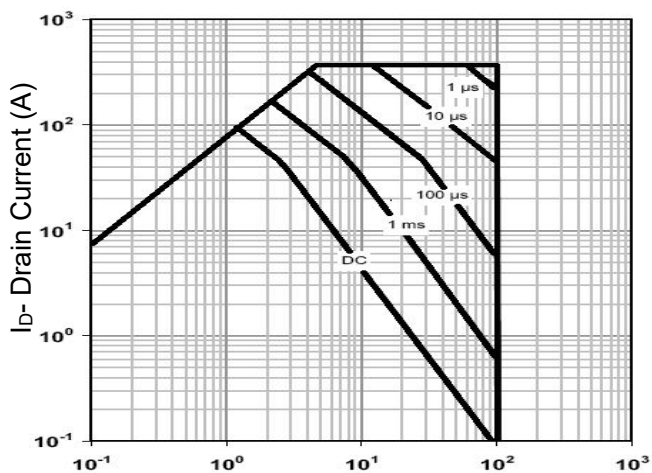
**Figure 6 Source- Drain Diode Forward**



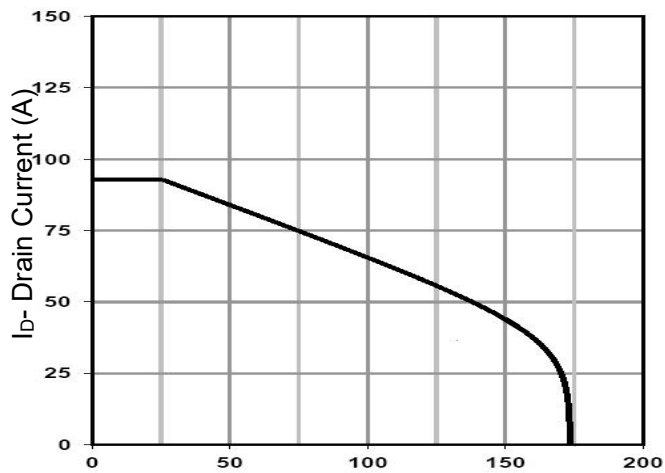
Vds Drain-Source Voltage (V)  
**Figure 7 Capacitance vs Vds**



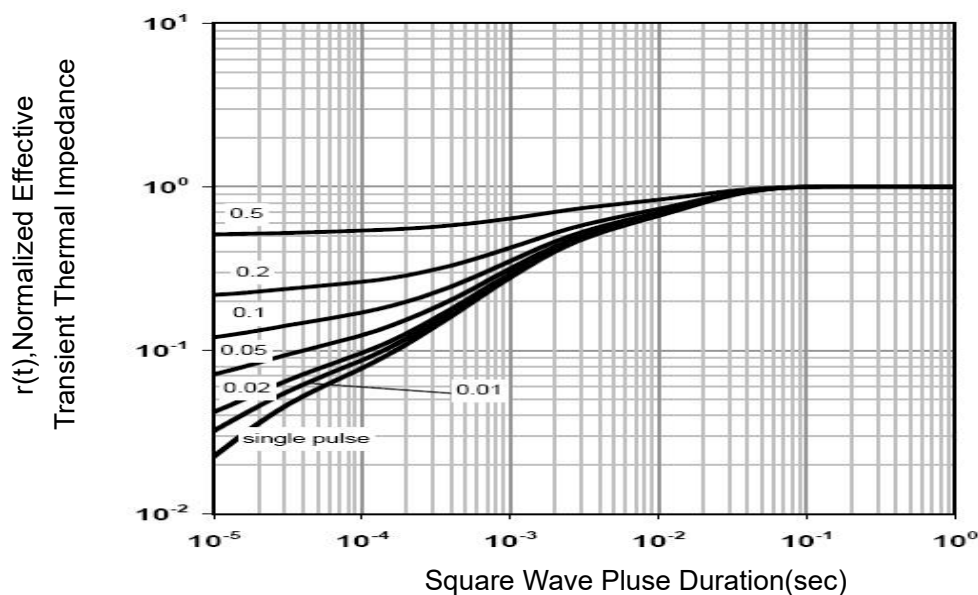
T<sub>J</sub>-Junction Temperature(°C)  
**Figure 9 Power De-rating**



Vds Drain-Source Voltage (V)  
**Figure 8 Safe Operation Area**

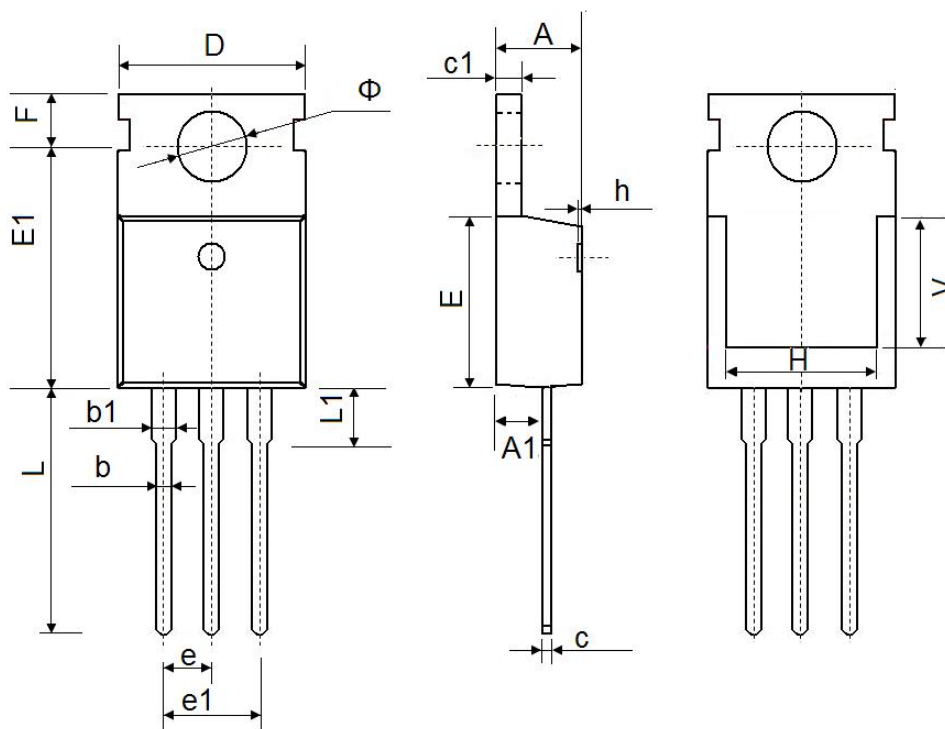


T<sub>J</sub>-Junction Temperature (°C)  
**Figure 10 Current De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## TO-220-3L Package Information



| Symbol | Dimensions In Millimeters |        | Dimensions In Inches |       |
|--------|---------------------------|--------|----------------------|-------|
|        | Min.                      | Max.   | Min.                 | Max.  |
| A      | 4.400                     | 4.600  | 0.173                | 0.181 |
| A1     | 2.250                     | 2.550  | 0.089                | 0.100 |
| b      | 0.710                     | 0.910  | 0.028                | 0.036 |
| b1     | 1.170                     | 1.370  | 0.046                | 0.054 |
| c      | 0.330                     | 0.650  | 0.013                | 0.026 |
| c1     | 1.200                     | 1.400  | 0.047                | 0.055 |
| D      | 9.910                     | 10.250 | 0.390                | 0.404 |
| E      | 8.9500                    | 9.750  | 0.352                | 0.384 |
| E1     | 12.650                    | 12.950 | 0.498                | 0.510 |
| e      | 2.540 TYP.                |        | 0.100 TYP.           |       |
| e1     | 4.980                     | 5.180  | 0.196                | 0.204 |
| F      | 2.650                     | 2.950  | 0.104                | 0.116 |
| H      | 7.900                     | 8.100  | 0.311                | 0.319 |
| h      | 0.000                     | 0.300  | 0.000                | 0.012 |
| L      | 12.900                    | 13.400 | 0.508                | 0.528 |
| L1     | 2.850                     | 3.250  | 0.112                | 0.128 |
| V      | 6.900 REF.                |        | 0.276 REF.           |       |
| Φ      | 3.400                     | 3.800  | 0.134                | 0.150 |

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